

08-12-2005

FORM PTO-1594  
(Rev. 6-93)



103060776

U.S. DEPARTMENT  
OF COMMERCE

Patent and  
Trademark Office

Atty Docket #:  
**ONS00610**

8-105

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying part(ies):  
**Shanghai Larry Tu  
James Adams  
Mohammed Quddus  
Rajesh S. Nair**

Additional name(s) of conveying party(ies) is provided on attached sheet.

2. Name and address of receiving party(ies):  
**SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C. of  
5005 East McDowell Road, Phoenix, AZ 85008**

112941 U.S. PTO  
11/193725



3. Nature of conveyance:  
 Assignment       Merger  
 Security Agreement       Change of Name  
 Other

Execution date of conveyance: **July 27, 2005; July 27, 2005; July 28, 2005; and July 20, 2005, respectively.**

Additional name(s) & address(es) attached?       Yes       No

4. Application number(s) or patent number(s):  
If this document is being filed together with a new application, the execution date of the application is:

**July 27, 2005; July 27, 2005; July 28, 2005; and July 20, 2005, respectively.**

A. Patent Application No.(s):

B. Patent No.(s):

Additional numbers attached?       Yes       No

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name: **SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C.**  
Internal Address: **Patent Administration - A700**  
Street Address: **P. O. Box 62890**  
City, State, Zip: **Phoenix, Arizona 85082-2890**

6. Total number of applications and patents involved:  
7. Total fee (37 C.F.R. 3.41).....**\$40.00**  
 Enclosed  
 Authorized to be charged to deposit account  
8. Deposit account number: **501086**

**DO NOT USE THIS SPACE**

9. Statement and signature.  
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Bradley Botsch      34,552  
Name of Person Signing      Reg. No.

July 26, 2005  
Date

Total number of pages including cover sheet, attachments, and document: **4**

OMB No. 0651-0011 (exp. 4/94)

08/11/2005 GT011    0000044 501086    11193725  
01 FC:8021      40.00 DA

**PATENT  
REEL: 016867 FRAME: 0606**

**ASSIGNMENT & AGREEMENT**

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

<u>Name</u>	<u>of (City/State/Country)</u>
<b>Shanghai Larry Tu</b>	PHOENIX, Arizona, USA;
<b>James Adams</b>	TEMPE, Arizona, USA;
<b>Mohammed Quddus</b>	CHANDLER, Arizona, USA;
<b>Rajesh S. Nair</b>	MILPITAS, California, USA;

have sold, assigned, and transferred, and do hereby sell assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a limited liability Company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain inventions relating to improvements in

**SEMICONDUCTOR STRUCTURE WITH IMPROVED ON RESISTANCE AND BREAKDOWN VOLTAGE  
(Attorney Docket No. ONS00471),**

described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof. We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



